What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	18
Program Memory Size	16KB (5.5K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 9x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f16ka101-i-ss

TABLE 1-2: PIC24F16KA102 FAMILY PINOUT DESCRIPTIONS (CONTINUED)

Function	Pin Number				I/O	Input Buffer	Description
	20-Pin PDIP/SSOP/SOIC	20-Pin QFN	28-Pin SPDIP/SSOP/SOIC	28-Pin QFN			
T1CK	10	7	12	9	I	ST	Timer1 Clock
T2CK	18	15	26	23	I	ST	Timer2 Clock
T3CK	18	15	26	23	I	ST	Timer3 Clock
$\overline{\text{U1CTS}}$	12	9	17	14	I	ST	UART1 Clear to Send Input
$\overline{\text{U1RTS}}$	13	10	18	15	O	—	UART1 Request to Send Output
U1RX	6	3	6	3	I	ST	UART1 Receive
U1TX	11	8	16	13	O	—	UART1 Transmit Output
VDD	20	17	13, 28	10, 25	P	—	Positive Supply for Peripheral Digital Logic and I/O Pins
VPP	1	18	1	26	P	—	Programming Mode Entry Voltage
VREF-	3	20	3	28	I	ANA	A/D and Comparator Reference Voltage (low) Input
VREF+	2	19	2	27	I	ANA	A/D and Comparator Reference Voltage (high) Input
VSS	19	16	8, 27	5, 24	P	—	Ground Reference for Logic and I/O Pin

Legend: ST = Schmitt Trigger input buffer, ANA = Analog level input/output, I^2C™ = I^2C/SMBus input buffer

Note 1: Alternative multiplexing when the I2C1SEL Configuration bit is cleared.

2.4.1 CONSIDERATIONS FOR CERAMIC CAPACITORS

In recent years, large value, low-voltage, surface-mount ceramic capacitors have become very cost effective in sizes up to a few tens of microfarad. The low-ESR, small physical size and other properties make ceramic capacitors very attractive in many types of applications.

Ceramic capacitors are suitable for use with the internal voltage regulator of this microcontroller. However, some care is needed in selecting the capacitor to ensure that it maintains sufficient capacitance over the intended operating range of the application.

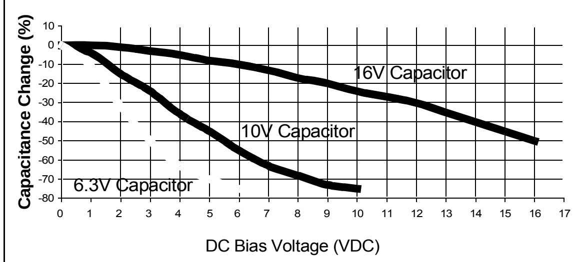
Typical low-cost, 10 µF ceramic capacitors are available in X5R, X7R and Y5V dielectric ratings (other types are also available, but are less common). The initial tolerance specifications for these types of capacitors are often specified as ±10% to ±20% (X5R and X7R), or -20%/+80% (Y5V). However, the effective capacitance that these capacitors provide in an application circuit will also vary based on additional factors, such as the applied DC bias voltage and the temperature. The total in-circuit tolerance is, therefore, much wider than the initial tolerance specification.

The X5R and X7R capacitors typically exhibit satisfactory temperature stability (ex: ±15% over a wide temperature range, but consult the manufacturer's data sheets for exact specifications). However, Y5V capacitors typically have extreme temperature tolerance specifications of +22%/-82%. Due to the extreme temperature tolerance, a 10 µF nominal rated Y5V type capacitor may not deliver enough total capacitance to meet minimum internal voltage regulator stability and transient response requirements. Therefore, Y5V capacitors are not recommended for use with the internal regulator if the application must operate over a wide temperature range.

In addition to temperature tolerance, the effective capacitance of large value ceramic capacitors can vary substantially, based on the amount of DC voltage applied to the capacitor. This effect can be very significant, but is often overlooked or is not always documented.

A typical DC bias voltage vs. capacitance graph for X7R type capacitors is shown in Figure 2-4.

FIGURE 2-4: DC BIAS VOLTAGE vs. CAPACITANCE CHARACTERISTICS



When selecting a ceramic capacitor to be used with the internal voltage regulator, it is suggested to select a high-voltage rating, so that the operating voltage is a small percentage of the maximum rated capacitor voltage. For example, choose a ceramic capacitor rated at 16V for the 3.3V or 2.5V core voltage. Suggested capacitors are shown in Table 2-1.

2.5 ICSP Pins

The PGC and PGD pins are used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of ohms, not to exceed 100Ω.

Pull-up resistors, series diodes and capacitors on the PGC and PGD pins are not recommended as they will interfere with the programmer/debugger communications to the device. If such discrete components are an application requirement, they should be removed from the circuit during programming and debugging. Alternatively, refer to the AC/DC characteristics and timing requirements information in the respective device Flash programming specification for information on capacitive loading limits, and pin input voltage high (V_{IH}) and input low (V_{IL}) requirements.

For device emulation, ensure that the “Communication Channel Select” (i.e., PGCx/PGDx pins), programmed into the device, matches the physical connections for the ICSP to the Microchip debugger/emulator tool.

For more information on available Microchip development tools connection requirements, refer to .

2.6 External Oscillator Pins

Many microcontrollers have options for at least two oscillators: a high-frequency primary oscillator and a low-frequency secondary oscillator (refer to **Section 9.0 “Oscillator Configuration”** for details).

The oscillator circuit should be placed on the same side of the board as the device. Place the oscillator circuit close to the respective oscillator pins with no more than 0.5 inch (12 mm) between the circuit components and the pins. The load capacitors should be placed next to the oscillator itself, on the same side of the board.

Use a grounded copper pour around the oscillator circuit to isolate it from surrounding circuits. The grounded copper pour should be routed directly to the MCU ground. Do not run any signal traces or power traces inside the ground pour. Also, if using a two-sided board, avoid any traces on the other side of the board where the crystal is placed.

Layout suggestions are shown in Figure 2-5. In-line packages may be handled with a single-sided layout that completely encompasses the oscillator pins. With fine-pitch packages, it is not always possible to completely surround the pins and components. A suitable solution is to tie the broken guard sections to a mirrored ground layer. In all cases, the guard trace(s) must be returned to ground.

In planning the application’s routing and I/O assignments, ensure that adjacent port pins and other signals, in close proximity to the oscillator, are benign (i.e., free of high frequencies, short rise and fall times, and other similar noise).

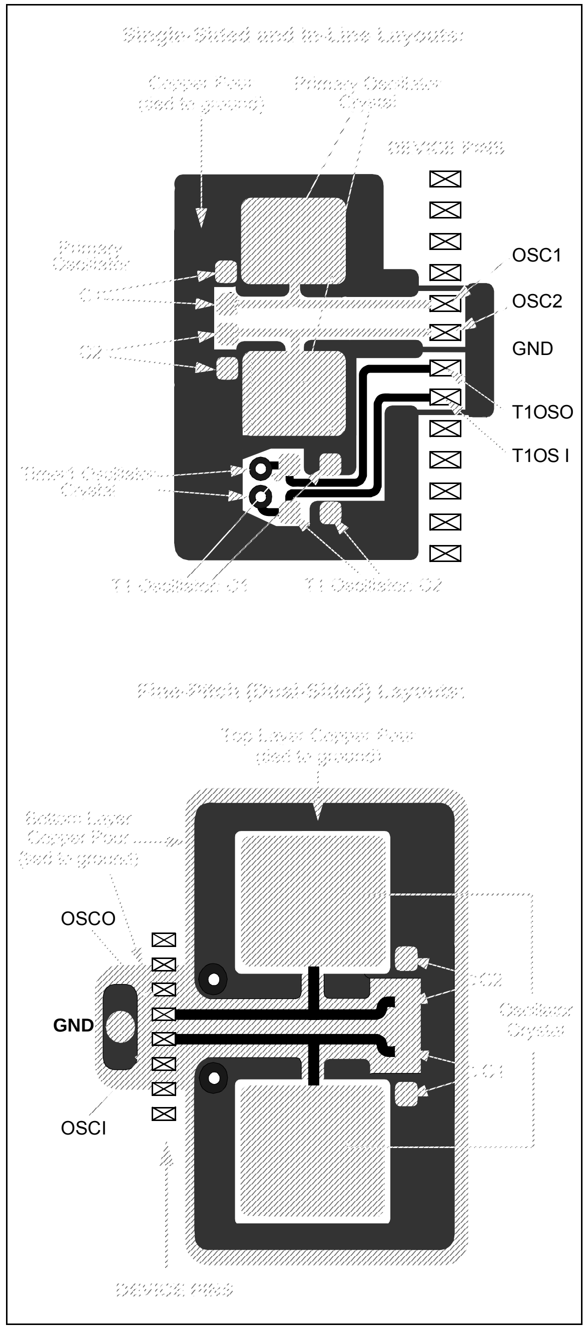
For additional information and design guidance on oscillator circuits, please refer to these Microchip Application Notes, available at the corporate web site (www.microchip.com):

- *AN826, “Crystal Oscillator Basics and Crystal Selection for rfPIC™ and PICmicro® Devices”*
- *AN849, “Basic PICmicro® Oscillator Design”*
- *AN943, “Practical PICmicro® Oscillator Analysis and Design”*
- *AN949, “Making Your Oscillator Work”*

2.7 Unused I/Os

Unused I/O pins should be configured as outputs and driven to a logic low state. Alternatively, connect a 1 kΩ to 10 kΩ resistor to VSS on unused pins and drive the output to logic low.

FIGURE 2-5: SUGGESTED PLACEMENT OF THE OSCILLATOR CIRCUIT



3.2 CPU Control Registers

REGISTER 3-1: SR: ALU STATUS REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HSC
—	—	—	—	—	—	—	DC
bit 15							bit 8

R/W-0, HSC[1]	R/W-0, HSC[1]	R/W-0, HSC[1]	R-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC	R/W-0, HSC
IPL2[2]	IPL1[2]	IPL0[2]	RA	N	OV	Z	C
bit 7							bit 0

Legend:	HSC = Hardware Settable/Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8 **DC:** ALU Half Carry/Borrow bit
1 = A carry-out from the 4th low-order bit (for byte-sized data) or 8th low-order bit (for word-sized data) of the result occurred
0 = No carry-out from the 4th or 8th low-order bit of the result has occurred

bit 7-5 **IPL<2:0>:** CPU Interrupt Priority Level Status bits[1,2]
111 = CPU interrupt priority level is 7 (15); user interrupts disabled
110 = CPU interrupt priority level is 6 (14)
101 = CPU Interrupt priority level is 5 (13)
100 = CPU interrupt priority level is 4 (12)
011 = CPU interrupt priority level is 3 (11)
010 = CPU interrupt priority level is 2 (10)
001 = CPU interrupt priority level is 1 (9)
000 = CPU interrupt priority level is 0 (8)

bit 4 **RA:** REPEAT Loop Active bit
1 = REPEAT loop in progress
0 = REPEAT loop not in progress

bit 3 **N:** ALU Negative bit
1 = Result was negative
0 = Result was non-negative (zero or positive)

bit 2 **OV:** ALU Overflow bit
1 = Overflow occurred for signed (2’s complement) arithmetic in this arithmetic operation
0 = No overflow has occurred

bit 1 **Z:** ALU Zero bit
1 = An operation, which effects the Z bit, has set it at some time in the past
0 = The most recent operation, which effects the Z bit, has cleared it (i.e., a non-zero result)

bit 0 **C:** ALU Carry/$\overline{\text{Borrow}}$ bit
1 = A carry-out from the Most Significant bit (MSb) of the result occurred
0 = No carry-out from the Most Significant bit (MSb) of the result occurred

Note 1: The IPL Status bits are read-only when NSTDIS (INTCON1<15>) = 1.
2: The IPL Status bits are concatenated with the IPL3 bit (CORCON<3>) to form the CPU Interrupt Priority Level (IPL). The value in parentheses indicates the IPL when IPL3 = 1.

TABLE 4-17: REAL-TIME CLOCK AND CALENDAR REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ALRMVAL	0620	Alarm Value Register Window Based on ALRMPTR<15:0>																xxxx
ALCFGRPT	0622	ALRMEN	CHIME	AMASK3	AMASK2	AMASK1	AMASK0	ALRMPTR1	ALRMPTR0	ARPT7	ARPT6	ARPT5	ARPT4	ARPT3	ARPT2	ARPT1	ARPT0	0000
RTCVAL	0624	RTCC Value Register Window Based on RTCPTR<15:0>																xxxx
RCFGCAL	0626	RTCEN	—	RTCWREN	RTCSYNC	HALFSEC	RTCOE	RTCPTR1	RTCPTR0	CAL7	CAL6	CAL5	CAL4	CAL3	CAL2	CAL1	CAL0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-18: DUAL COMPARATOR REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CMSTAT	0630	CMSIDL	—	—	—	—	—	C2EVT	C1EVT	—	—	—	—	—	—	C2OUT	C1OUT	0000
CVRCON	0632	—	—	—	—	—	—	—	—	CVREN	CVROE	CVRR	CVRSS	CVR3	CVR2	CVR1	CVR0	0000
CM1CON	0634	CON	COE	CPOL	CLPWR	—	—	CEVT	COUT	EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0	0000
CM2CON	0636	CON	COE	CPOL	CLPWR	—	—	CEVT	COUT	EVPOL1	EVPOL0	—	CREF	—	—	CCH1	CCH0	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-19: CRC REGISTER MAP

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
CRCCON	0640	—	—	CSIDL	VWORD4	VWORD3	VWORD2	VWORD1	VWORD0	CRCFUL	CRCMPT	—	CRCGO	PLEN3	PLEN2	PLEN1	PLEN0	0040
CRCXOR	0642	X<15:1>															—	0000
CRCDAT	0644	CRC Data Input Register																0000
CRCWDAT	0646	CRC Result Register																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

7.0 RESETS

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Resets, refer to the *"PIC24F Family Reference Manual"*, **Section 40. "Reset with Programmable Brown-out Reset"** (DS39728).

The Reset module combines all Reset sources and controls the device Master Reset Signal, SYSRST. The following is a list of device Reset sources:

- POR: Power-on Reset
- MCLR: Pin Reset
- SWR: RESET Instruction
- WDTR: Watchdog Timer Reset
- BOR: Brown-out Reset
- Low-Power BOR/Deep Sleep BOR
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Opcode Reset
- UWR: Uninitialized W Register Reset

Figure 7-1 displays a simplified block diagram of the Reset module.

Any active source of Reset will make the SYSRST signal active. Many registers associated with the CPU and peripherals are forced to a known Reset state. Most registers are unaffected by a Reset; their status is unknown on a Power-on Reset (POR) and unchanged by all other Resets.

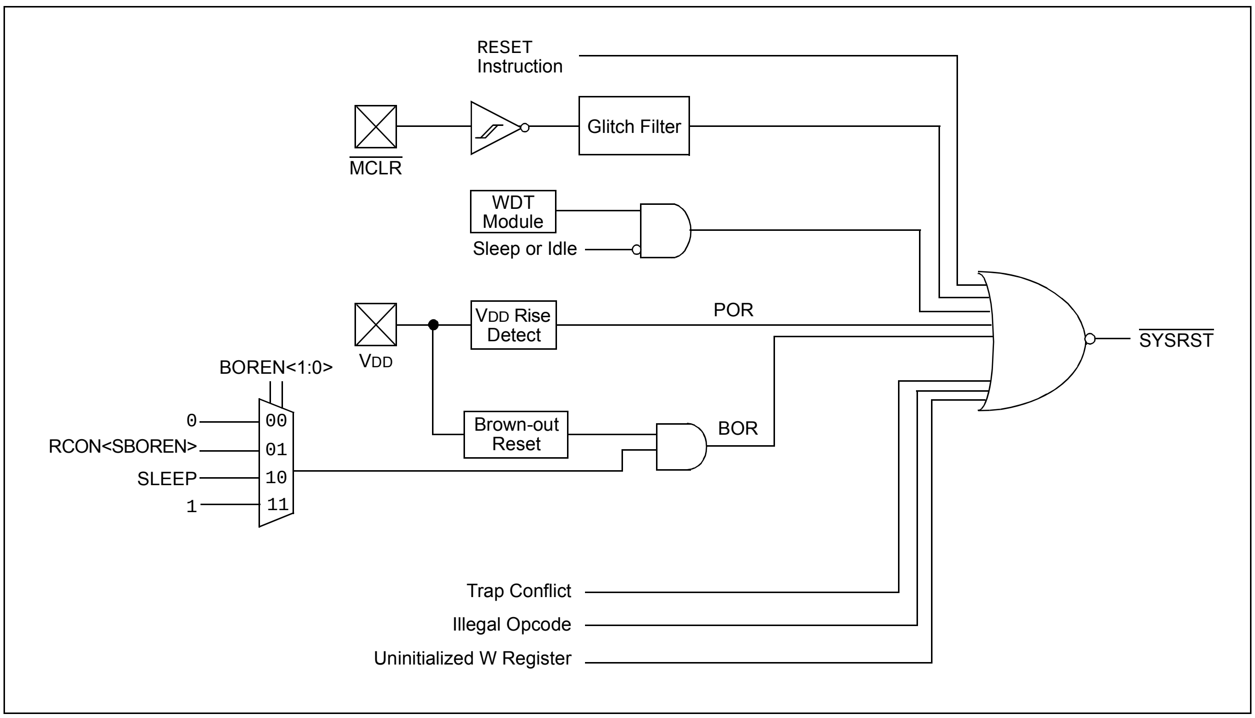
> **Note:** Refer to the specific peripheral or CPU section of this manual for register Reset states.

All types of device Reset will set a corresponding status bit in the RCON register to indicate the type of Reset (see Register 7-1). A POR will clear all bits except for the BOR and POR bits (RCON<1:0>) which are set. The user may set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software will not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer (WDT) and device power-saving states. The function of these bits is discussed in other sections of this manual.

> **Note:** The status bits in the RCON register should be cleared after they are read so that the next RCON register value, after a device Reset, will be meaningful.

FIGURE 7-1: RESET SYSTEM BLOCK DIAGRAM



7.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) will have a relatively long start-up time. Therefore, one or more of the following conditions is possible after $\overline{\text{SYSRST}}$ is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer (OST) has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

7.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it will begin to monitor the system clock source when $\overline{\text{SYSRST}}$ is released. If a valid clock source is not available at this time, the device will automatically switch to the FRC oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine (TSR).

7.3 Special Function Register Reset States

Most of the Special Function Registers (SFRs) associated with the PIC24F CPU and peripherals are reset to a particular value at a device Reset. The SFRs are grouped by their peripheral or CPU function and their Reset values are specified in each section of this manual.

The Reset value for each SFR does not depend on the type of Reset with the exception of four registers. The Reset value for the Reset Control register, RCON, will depend on the type of device Reset. The Reset value for the Oscillator Control register, OSCCON, will depend on the type of Reset and the programmed values of the FNOSC bits in the Flash Configuration Word (FOSCSEL); see Table 7-2. The RCFGCAL and NVMCON registers are only affected by a POR.

7.4 Deep Sleep BOR (DSBOR)

Deep Sleep BOR is a very low-power BOR circuitry, used when the device is in Deep Sleep mode. Due to low-current consumption, accuracy may vary.

The DSBOR trip point is around 2.0V. DSBOR is enabled by configuring DSBOREN (FDS<6>) = `1`. DSBOREN will re-arm the POR to ensure the device will reset if V_{DD} drops below the POR threshold.

7.5 Brown-out Reset (BOR)

The PIC24F16KA102 family devices implement a BOR circuit, which provides the user several configuration and power-saving options. The BOR is controlled by the BORV<1:0> and BOREN<1:0> Configuration bits (FPOR<6:5,1:0>). There are a total of four BOR configurations, which are provided in Table 7-3.

The BOR threshold is set by the BORV<1:0> bits. If BOR is enabled (any values of BOREN<1:0>, except '`00`'), any drop of V_{DD} below the set threshold point will reset the device. The chip will remain in BOR until V_{DD} rises above threshold.

If the Power-up Timer is enabled, it will be invoked after V_{DD} rises above the threshold. Then, it will keep the chip in Reset for an additional time delay, T_{PWRT}, if V_{DD} drops below the threshold while the Power-up Timer is running. The chip goes back into a BOR and the Power-up Timer will be initialized. Once V_{DD} rises above the threshold, the Power-up Timer will execute the additional time delay.

BOR and the Power-up Timer are independently configured. Enabling the BOR Reset does not automatically enable the PWRT.

7.5.1 SOFTWARE ENABLED BOR

When BOREN<1:0> = `01`, the BOR can be enabled or disabled by the user in software. This is done with the control bit, SBOREN (RCON<13>). Setting SBOREN enables the BOR to function as previously described. Clearing the SBOREN disables the BOR entirely. The SBOREN bit operates only in this mode; otherwise, it is read as '`0`'.

Placing BOR under software control gives the user the additional flexibility of tailoring the application to its environment without having to reprogram the device to change the BOR configuration. It also allows the user to tailor the incremental current that the BOR consumes. While the BOR current is typically very small, it may have some impact in low-power applications.

Note:	Even when the BOR is under software control, the BOR Reset voltage level is still set by the BORV<1:0> Configuration bits; it can not be changed in software.

REGISTER 8-19: IPC7: INTERRUPT PRIORITY CONTROL REGISTER 7

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	U2TXIP2	U2TXIP1	U2TXIP0	—	U2RXIP2	U2RXIP1	U2RXIP0
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	INT2IP2	INT2IP1	INT2IP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **U2TXIP<2:0>:** UART2 Transmitter Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as ‘0’

bit 10-8 **U2RXIP<2:0>:** UART2 Receiver Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 7 **Unimplemented:** Read as ‘0’

bit 6-4 **INT2IP<2:0>:** External Interrupt 2 Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as ‘0’

REGISTER 8-24: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

R-0	U-0	R/W-0	U-0	R-0	R-0	R-0	R-0
CPUIRQ	—	VHOLD	—	ILR3	ILR2	ILR1	ILR0
bit 15							bit 8

U-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
—	VECNUM6	VECNUM5	VECNUM4	VECNUM3	VECNUM2	VECNUM1	VECNUM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CPUIRQ:** Interrupt Request from Interrupt Controller CPU bit
1 = An interrupt request has occurred but has not yet been Acknowledged by the CPU (this will happen when the CPU priority is higher than the interrupt priority)
0 = No interrupt request is left unacknowledged

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **VHOLD:** Allows Vector Number Capture and Changes what Interrupt is Stored in VECNUM bit
1 = VECNUM will contain the value of the highest priority pending interrupt, instead of the current interrupt
0 = VECNUM will contain the value of the last Acknowledged interrupt (last interrupt that has occurred with higher priority than the CPU, even if other interrupts are pending)

bit 12 **Unimplemented:** Read as ‘0’

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits
1111 = CPU Interrupt Priority Level is 15
•
•
•
0001 = CPU Interrupt Priority Level is 1
0000 = CPU Interrupt Priority Level is 0

bit 7 **Unimplemented:** Read as ‘0’

bit 6-0 **VECNUM<6:0>:** Vector Number of Pending Interrupt bits
0111111 = Interrupt Vector pending is Number 135
•
•
•
0000001 = Interrupt Vector pending is Number 9
0000000 = Interrupt Vector pending is Number 8

REGISTER 9-2: CLKDIV: CLOCK DIVIDER REGISTER

R/W-0	R/W-0	R/W-1	R/W-1	R/W-0	R/W-0	R/W-0	R/W-1
ROI	DOZE2	DOZE1	DOZE0	DOZEN(1)	RCDIV2	RCDIV1	RCDIV0
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ROI:** Recover on Interrupt bit
1 = Interrupts clear the DOZEN bit and reset the CPU and peripheral clock ratio to 1:1
0 = Interrupts have no effect on the DOZEN bit

bit 14-12 **DOZE<2:0>:** CPU and Peripheral Clock Ratio Select bits
111 = 1:128
110 = 1:64
101 = 1:32
100 = 1:16
011 = 1:8
010 = 1:4
001 = 1:2
000 = 1:1

bit 11 **DOZEN:** DOZE Enable bit(1)
1 = DOZE<2:0> bits specify the CPU and peripheral clock ratio
0 = CPU and peripheral clock ratio are set to 1:1

bit 10-8 **RCDIV<2:0>:** FRC Postscaler Select bits
When OSCCON (COSC<2:0>) = 111:
111 = 31.25 kHz (divide by 256)
110 = 125 kHz (divide by 64)
101 = 250 kHz (divide by 32)
100 = 500 kHz (divide by 16)
011 = 1 MHz (divide by 8)
010 = 2 MHz (divide by 4)
001 = 4 MHz (divide by 2) (default)
000 = 8 MHz (divide by 1)
When OSCCON (COSC<2:0>) = 110:
111 = 1.95 kHz (divide by 256)
110 = 7.81 kHz (divide by 64)
101 = 15.62 kHz (divide by 32)
100 = 31.25 kHz (divide by 16)
011 = 62.5 kHz (divide by 8)
010 = 125 kHz (divide by 4)
001 = 250 kHz (divide by 2) (default)
000 = 500 kHz (divide by 1)

bit 7-0 **Unimplemented:** Read as ‘0’

Note 1: This bit is automatically cleared when the ROI bit is set and an interrupt occurs.

NOTES:

10.0 POWER-SAVING FEATURES

> **Note:** This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"PIC24F Family Reference Manual"*, **"Section 39. Power-Saving Features with Deep Sleep"** (DS39727).

The PIC24F16KA102 family of devices provides the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of circuits being clocked constitutes lower consumed power. All PIC24F devices manage power consumption in four different ways:

- Clock frequency
- Instruction-based Sleep, Idle and Deep Sleep modes
- Software controlled Doze mode
- Selective peripheral control in software

Combinations of these methods can be used to selectively tailor an application's power consumption, while still maintaining critical application features, such as timing-sensitive communications.

10.1 Clock Frequency and Clock Switching

PIC24F devices allow for a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSC bits. The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 9.0 "Oscillator Configuration"**.

10.2 Instruction-Based Power-Saving Modes

PIC24F devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution; Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. Deep Sleep mode stops clock operation, code execution and all peripherals except RTCC and DSWDT. It also freezes I/O states and removes power to SRAM and Flash memory.

The assembly syntax of the PWRSAV instruction is shown in Example 10-1.

> **Note:** SLEEP_MODE and IDLE_MODE are constants, defined in the assembler include file, for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

10.2.1 SLEEP MODE

Sleep mode includes these features:

- The system clock source is shut down. If an on-chip oscillator is used, it is turned off.
- The device current consumption will be reduced to a minimum provided that no I/O pin is sourcing current.
- The I/O pin directions and states are frozen.
- The Fail-Safe Clock Monitor does not operate during Sleep mode since the system clock source is disabled.
- The LPRC clock will continue to run in Sleep mode if the WDT or RTCC, with LPRC as the clock source, is enabled.
- The WDT, if enabled, is automatically cleared prior to entering Sleep mode.
- Some device features or peripherals may continue to operate in Sleep mode. This includes items, such as the input change notification on the I/O ports, or peripherals that use an external clock input. Any peripheral that requires the system clock source for its operation will be disabled in Sleep mode.

The device will wake-up from Sleep mode on any of these events:

- On any interrupt source that is individually enabled
- On any form of device Reset
- On a WDT time-out

On wake-up from Sleep, the processor will restart with the same clock source that was active when Sleep mode was entered.

EXAMPLE 10-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV     #SLEEP_MODE    ; Put the device into SLEEP mode
PWRSAV     #IDLE_MODE     ; Put the device into IDLE mode
BSET       DSCON, #DSEN   ; Enable Deep Sleep
PWRSAV     #SLEEP_MODE    ; Put the device into Deep SLEEP mode
```


10.2.4.2 Exiting Deep Sleep Mode

Deep Sleep mode exits on any one of the following events:

- POR event on V_{DD} supply. If there is no DSBOR circuit to re-arm the V_{DD} supply POR circuit, the external V_{DD} supply must be lowered to the natural arming voltage of the POR circuit.
- DSWDT time-out. When the DSWDT timer times out, the device exits Deep Sleep.
- RTCC alarm (if RTCEN = `1`).
- Assertion (‘`0`’) of the $\overline{\text{MCLR}}$ pin.
- Assertion of the INT0 pin (if the interrupt was enabled before Deep Sleep mode was entered). The polarity configuration is used to determine the assertion level (‘`0`’ or ‘`1`’) of the pin that will cause an exit from Deep Sleep mode. Exiting from Deep Sleep mode requires a change on the INT0 pin while in Deep Sleep mode.

Note:	Any interrupt pending when entering Deep Sleep mode is cleared,

Exiting Deep Sleep mode generally does not retain the state of the device and is equivalent to a Power-on Reset (POR) of the device. Exceptions to this include the RTCC (if present), which remains operational through the wake-up, the DSGPRx registers and the DSWDT bit.

Wake-up events that occur from the time Deep Sleep exits until the time the POR sequence completes are ignored and are not be captured in the DSWAKE register.

The sequence for exiting Deep Sleep mode is:

1. After a wake-up event, the device exits Deep Sleep and performs a POR. The DSEN bit is cleared automatically. Code execution resumes at the Reset vector.
2. To determine if the device exited Deep Sleep, read the Deep Sleep bit, DPSLP (RCON<10>). This bit will be set if there was an exit from Deep Sleep mode; if the bit is set, clear it.
3. Determine the wake-up source by reading the DSWAKE register.
4. Determine if a DSBOR event occurred during Deep Sleep mode by reading the DSBOR bit (DSCON<1>).
5. If application context data has been saved, read it back from the DSGPR0 and DSGPR1 registers.
6. Clear the RELEASE bit (DSCON<0>).

10.2.4.3 Saving Context Data with the DSGPR0/DSGPR1 Registers

As exiting Deep Sleep mode causes a POR, most Special Function Registers reset to their default POR values. In addition, because V_{DDCORE} power is not supplied in Deep Sleep mode, information in data RAM may be lost when exiting this mode.

Applications which require critical data to be saved prior to Deep Sleep may use the Deep Sleep General Purpose registers, DSGPR0 and DSGPR1, or data EEPROM (if available). Unlike other SFRs, the contents of these registers are preserved while the device is in Deep Sleep mode. After exiting Deep Sleep, software can restore the data by reading the registers and clearing the RELEASE bit (DSCON<0>).

10.2.4.4 I/O Pins During Deep Sleep

During Deep Sleep, the general purpose I/O pins retain their previous states and the Secondary Oscillator (SOSC) will remain running, if enabled. Pins that are configured as inputs (TRISx bit set), prior to entry into Deep Sleep, remain high-impedance during Deep Sleep. Pins that are configured as outputs (TRISx bit clear), prior to entry into Deep Sleep, remain as output pins during Deep Sleep. While in this mode, they continue to drive the output level determined by their corresponding LATx bit at the time of entry into Deep Sleep.

Once the device wakes back up, all I/O pins continue to maintain their previous states, even after the device has finished the POR sequence and is executing application code again. Pins configured as inputs during Deep Sleep remain high-impedance and pins configured as outputs continue to drive their previous value. After waking up, the TRIS and LAT registers, and the SOSCEN bit (OSCCON<1>) are reset. If firmware modifies any of these bits or registers, the I/O will not immediately go to the newly configured states. Once the firmware clears the RELEASE bit (DSCON<0>), the I/O pins are “released”. This causes the I/O pins to take the states configured by their respective TRIS and LAT bit values.

This means that keeping the SOSC running after waking up requires the SOSCEN bit to be set before clearing RELEASE.

If the Deep Sleep BOR (DSBOR) is enabled, and a DSBOR or a true POR event occurs during Deep Sleep, the I/O pins will be immediately released, similar to clearing the RELEASE bit. All previous state information will be lost, including the general purpose DSGPR0 and DSGPR1 contents.

If a $\overline{\text{MCLR}}$ Reset event occurs during Deep Sleep, the DSGPRx, DSCON and DSWAKE registers will remain valid, and the RELEASE bit will remain set. The state of the SOSC will also be retained. The I/O pins, however, will be reset to their $\overline{\text{MCLR}}$ Reset state. Since RELEASE is still set, changes to the SOSCEN bit (OSCCON<1>) cannot take effect until the RELEASE bit is cleared.

In all other Deep Sleep wake-up cases, application firmware must clear the RELEASE bit in order to reconfigure the I/O pins.

REGISTER 15-2: PADCFG1: PAD CONFIGURATION CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	SMBUSDEL(3)	OC1TRIS(2)	RTSECSEL1(1,4)	RTSECSEL0(1,4)	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-5 **Unimplemented:** Read as ‘0’

bit 3 **OC1TRIS:** OC1 Output Tri-State Select bit(2)
1 = OC1 output will not be active on the pin; OCPWM1 can still be used for internal triggers
0 = OC1 output will be active on the pin based on the OCPWM1 module settings

bit 0 **Unimplemented:** Read as ‘0’

Note 1: To enable the actual RTCC output, the RTCOE (RCFGCAL) bit needs to be set.
2: To enable the actual OC1 output, the OCPWM1 module has to be enabled.
3: Bit 4 is described in **Section 17.0 “Inter-Integrated Circuit (I2C™)”**.
4: Bits 2 and 1 are described in **Section 19.0 Real-Time Clock and Calendar (RTCC)**.

FIGURE 19-2: ALARM MASK SETTINGS

Alarm Mask Setting (AMASK<3:0>)	Day of the Week	Month		Day		Hours		Minutes		Seconds	
`0000` - Every half second `0001` - Every second											
`0010` - Every 10 seconds											s
`0011` - Every minute										s	s
`0100` - Every 10 minutes									m	s	s
`0101` - Every hour								m	m	s	s
`0110` - Every day						h	h	m	m	s	s
`0111` - Every week	d					h	h	m	m	s	s
`1000` - Every month				d	d	h	h	m	m	s	s
`1001` - Every year[(1)]		m	m	d	d	h	h	m	m	s	s

Note 1: Annually, except when configured for February 29.

20.0 PROGRAMMABLE CYCLIC REDUNDANCY CHECK (CRC) GENERATOR

Note:	This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information on Programmable Cyclic Redundancy Check, refer to the *"PIC24F Family Reference Manual"*, **Section 30. "Programmable Cyclic Redundancy Check (CRC)"** (DS39714).

The programmable Cyclic Redundancy Check (CRC) module in PIC24F devices is a software-configurable CRC checksum generator. The CRC algorithm treats a message as a binary bit stream and divides it by a fixed binary number.

The remainder from this division is considered the checksum. As in division, the CRC calculation is also an iterative process. The only difference is that these operations are done on modulo arithmetic based on mod2. For example, division is replaced with the XOR operation (i.e., subtraction without carry). The CRC algorithm uses the term, polynomial, to perform all of its calculations.

The divisor, dividend and remainder that are represented by numbers are termed as polynomials with binary coefficients.

The programmable CRC generator offers the following features:

- User-programmable polynomial CRC equation
- Interrupt output
- Data FIFO

The module implements a software-configurable CRC generator. The terms of the polynomial and its length can be programmed using the CRCXOR (X<15:1>) bits and the CRCCON (PLEN<3:0>) bits, respectively. Consider the CRC equation:

EQUATION 20-1: CRC

$$x^{16} + x^{12} + x^5 + 1$$

To program this polynomial into the CRC generator, the CRC register bits should be set as provided in Table 20-1.

TABLE 20-1: EXAMPLE CRC SETUP

Bit Name	Bit Value
PLEN<3:0>	1111
X<15:1>	000100000010000

The value of X<15:1>, the 12th bit and the 5th bit are set to '1', as required by the equation. The 0 bit required by the equation is always XORed. For a 16-bit polynomial, the 16th bit is also always assumed to be XORed; therefore, the X<15:1> bits do not have the 0 bit or the 16th bit.

The topology of a standard CRC generator is displayed in Figure 20-2.

FIGURE 20-1: CRC SHIFTER DETAILS

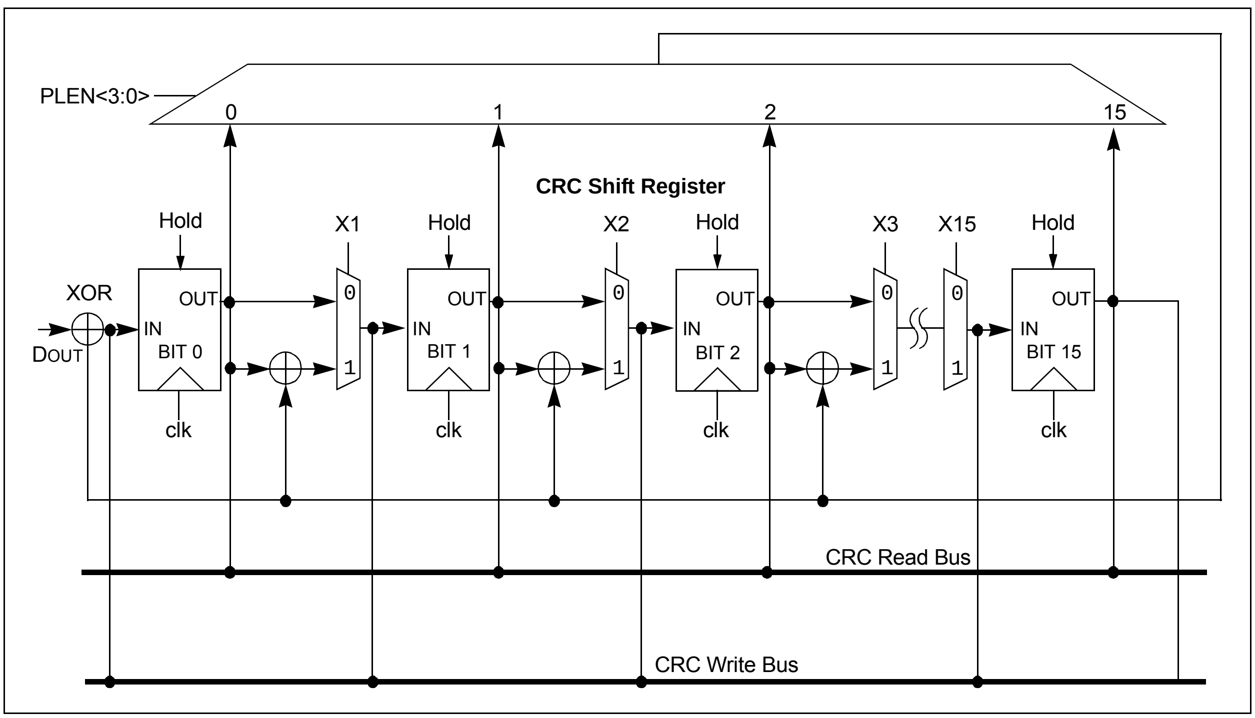
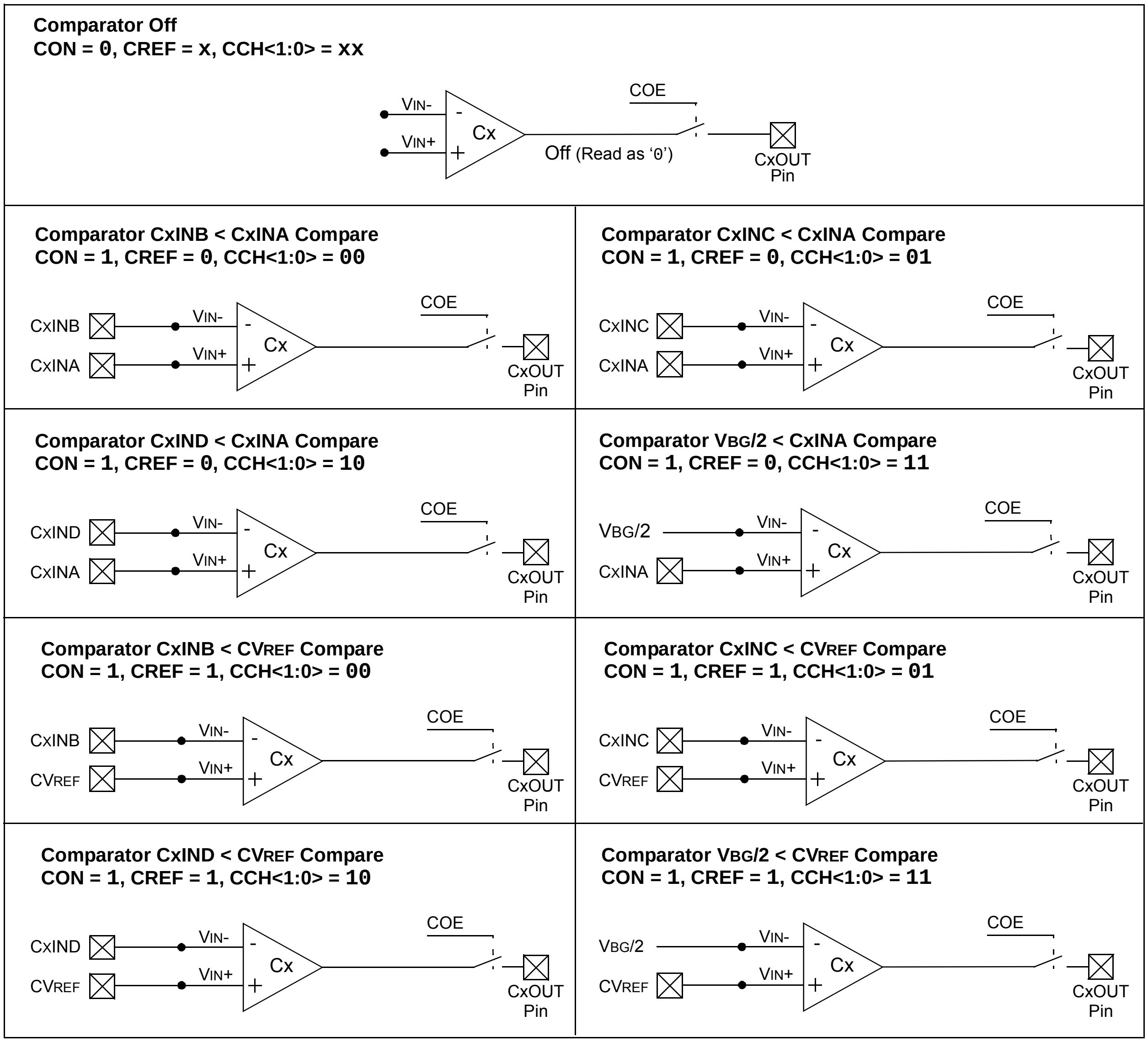


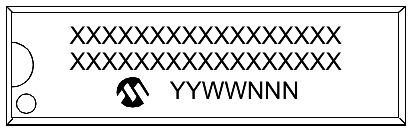
FIGURE 23-2: INDIVIDUAL COMPARATOR CONFIGURATIONS



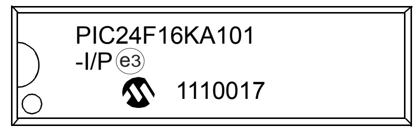
30.0 PACKAGING INFORMATION

30.1 Package Marking Information

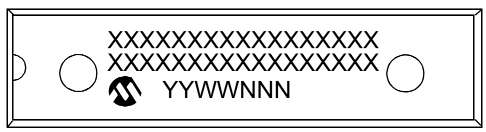
20-Lead PDIP



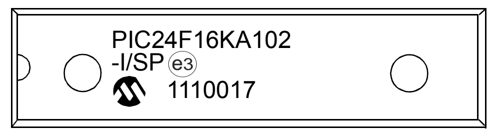
Example



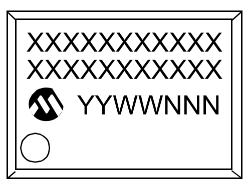
28-Lead SPDIP



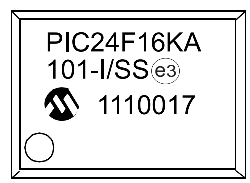
Example



20-Lead SSOP



Example



28-Lead SSOP

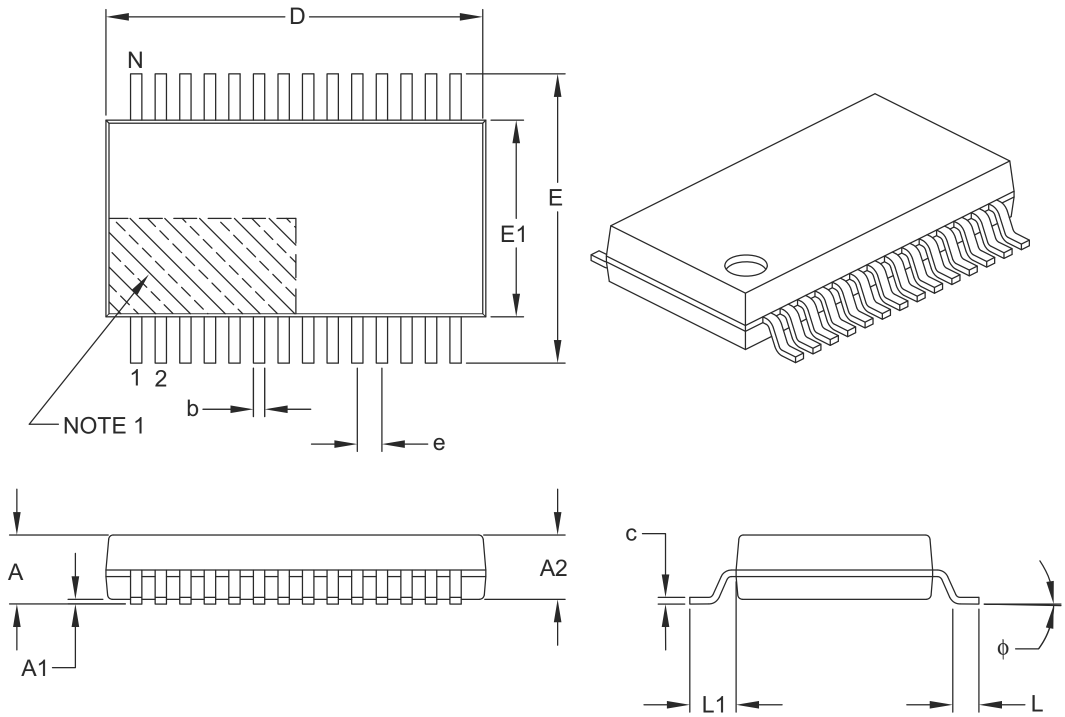
Example

Legend:	XX...X	Product-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	e3	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	φ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B